



Material Content Data Sheet



Sales Product Name	TLE6232GP			Issued	28. August 2013			
MA#	MA000691392							
Package	PG-DSO-36-48			Weight*	2047.14 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.568	0.86	0.86	8582	8582
leadframe	inorganic material	phosphorus	7723-14-0	0.383	0.02		187	
	non noble metal	zinc	7440-66-6	1.533	0.07		749	
	non noble metal	iron	7439-89-6	30.652	1.50		14973	
wire	non noble metal	copper	7440-50-8	1244.598	60.78	62.37	607969	623878
	non noble metal	copper	7440-50-8	2.640	0.13	0.13	1289	1289
	encapsulation	organic material	carbon black	1333-86-4	1.440	0.07		703
	plastics	epoxy resin	-	66.224	3.24		32350	
	inorganic material	silicondioxide	60676-86-0	652.164	31.86	35.17	318574	351627
leadfinish	non noble metal	tin	7440-31-5	16.150	0.79	0.79	7889	7889
plating	noble metal	silver	7440-22-4	0.741	0.04	0.04	362	362
solder	noble metal	silver	7440-22-4	0.196	0.01		96	
	non noble metal	tin	7440-31-5	0.130	0.01		64	
	non noble metal	lead	7439-92-1	12.718	0.62	0.64	6213	6373
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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